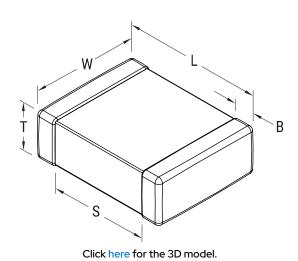


C1206C309DATACTU

Aliases (C1206C309DATAC7800) SMD Comm X8G HT150C, Ceramic, 3 pF, +/-0.5 pF, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Т	0.78mm +/-0.10mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

_	512.11.11. / 512.11.11.
W	1.6mm +/-0.2mm
Т	0.78mm +/-0.10mm
S	1.5mm MIN
В	0.5mm +/-0.25mm
Packaging Specifications	

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Specifications	
Capacitance	3 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.5 pF
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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